



TO-251 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	3	Si	7440-21-3	100.00%
Lead Frame	218	Cu	7440-50-08	99.81%
		Fe	7439-89-6	0.15%
		P	7723-14-0	0.04%
Solder	3	Pb	7439-92-1	95.50%
		Sn	7440-31-5	2.00%
		Ag	7440-22-4	2.50%
Wire	2	Al	7429-90-5	99.995%
		Ni	7440-02-0	0.005%
		Cu	7440-50-08	≥99.99%
Mold Compound	161	Epoxy ResinA	Trade secret	1~5%
		Epoxy ResinB	29690-82-2	1~5%
		Phenol Resin	Trade secret	1~5%
		Silica(aAmorphous)A	60676-86-0	70~90%
		Silica(Amorphous)B	7631-86-9	1~5%
		Carbon Black	1333-86-4	0.1~1%
Plating	3	Tin	7440-31-5	≥99.99%
Total	390			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.